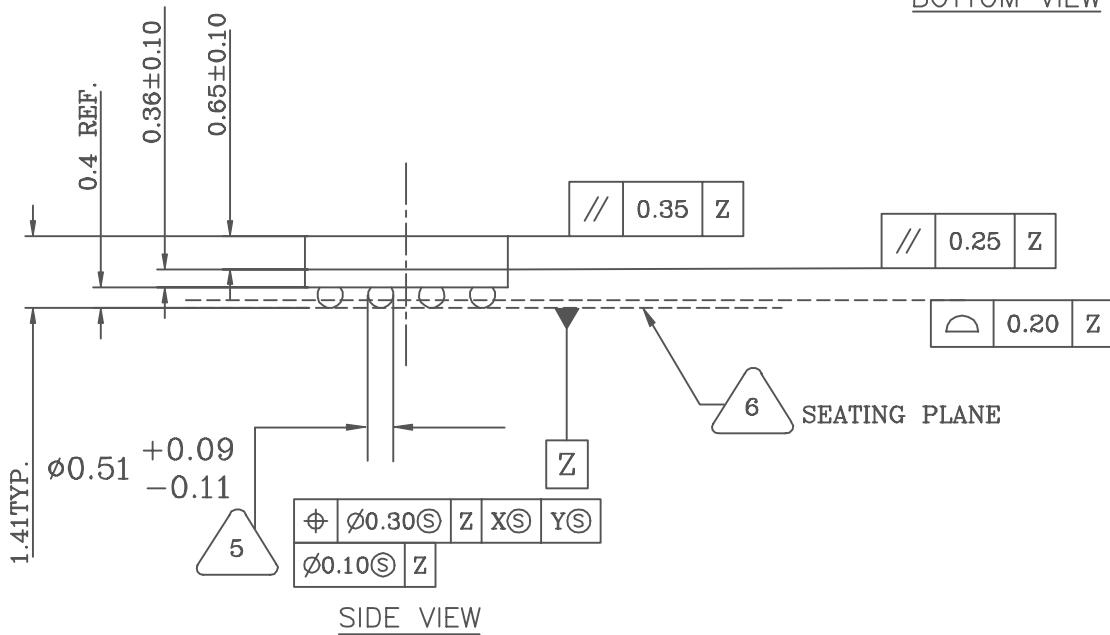
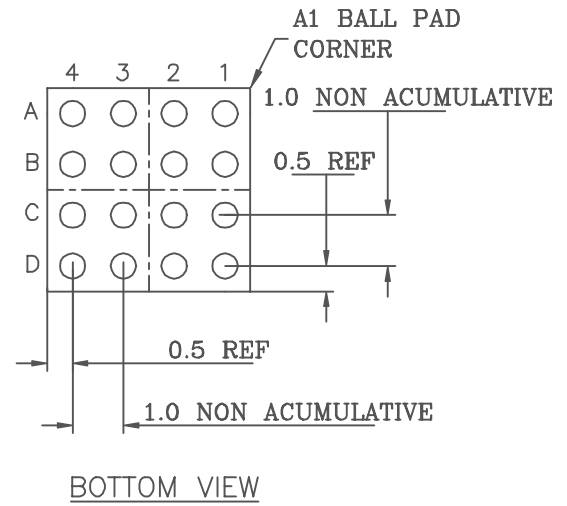
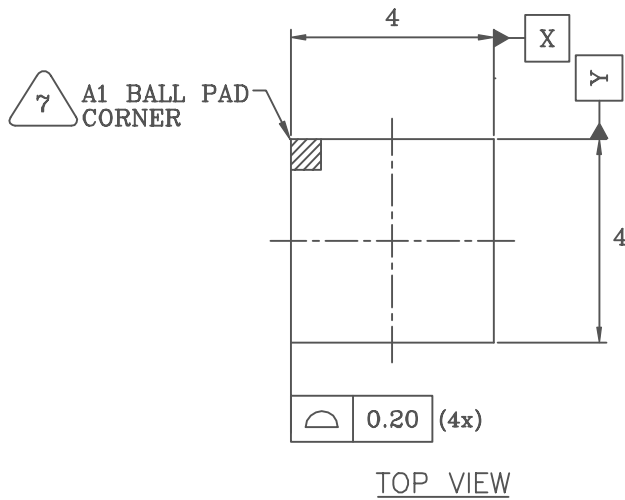


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	3/00	



NOTES:

- A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.
- PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE		 MARKETING OUTLINE – 16L CHIP SCALE BGA (4X4) 1.0MM PITCH, 1.41 THICK, 2 LAYER							
DOC. CONTROL:											
ENGR. MGR:											
MFG. ENGR:											
CHECKED BY:	TWM	3/00		SIZE	A	PSCH NO.		PART NO.	56-G6005-001	REV.	A
DRAWN BY:	NLK	3/00		SCALE	N/A	SHEET			1 of 1		
DO NOT SCALE DRAWING											